GL100MN1MPx

Surface Mount Type, High Power Output Infrared Emitting Diode

■ Features

1. Compact and thin SMD package
2. Top view and side view mountable
3. Plastic mold with resin lens
4. Peak emission wavelength: 940 nm TYP.
5. Narrow directivity angle ($\Delta\theta$ ±10° TYP.)
6. High power output (ϕ e: 6.0 mW MAX.)
7. Lead free and RoHS directive compliant

■ Agency Approvals/Compliance

1. Compliant with RoHS directive (2002/95/EC)
2. Content information about the six substances specified in “Management Methods for Control of Pollution Caused by Electronic Information Products Regulation” (popular name: China RoHS) (Chinese: 电子信息产品污染控制管理办法); refer to page 7.

■ Model Line-up

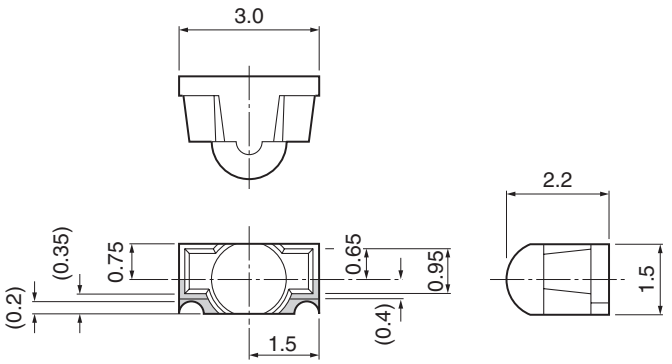
Model No.	Packaging	Mount Direction
GL100MN1MP	2000 pcs/reel	Side view
GL100MN1MP1	1500 pcs/reel	Top view

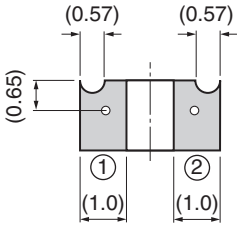
■ Applications

1. Office automation equipment
2. Audio visual equipment
3. Home appliances
4. Telecommunication equipment
5. Measuring equipment
6. Tooling machines
7. Computers

Sheet No.: D1-A00701EN
Date: November 30, 2007

■ External Dimensions

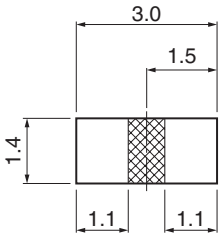




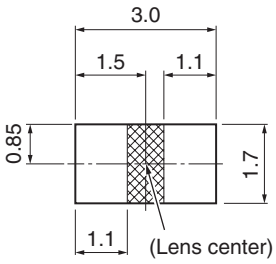
Pin Arrangement

No.	Name
①	Anode
②	Cathode

Viewed from PCB
(Side view Mounting)



Viewed from PCB
(Top view Mounting)



NOTES:

1. Unit: mm
2. Unspecified tolerance : ±0.2 mm
3. ( ) : Reference dimensions
4. ▭ Au-plated area
5. Do not allow circuit runs in ▨ area

■ Absolute Maximum Ratings

(Ta = 25°C)

Parameter	Symbol	Rating	Unit
Forward current	I_F	50	mA
Peak pulsed forward current *1	I_{FM}	0.5	A
Reverse voltage	V_R	6	V
Power dissipation	P	75	mW
Operating temperature	Topr	-30 to +85	°C
Storage temperature	Tstg	-40 to +95	°C
Soldering temperature *2	Tsol	240	°C

*1 Pulse width: 100 µs, Duty ratio: 0.01
*2 10 s (MAX.) see reflow profile on page 6.

■ Electro-optical Charactertistics

(Ta = 25°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Forward voltage	V_F	I_F = 20 mA	–	1.2	1.5	V
Peak forward voltage	V_{FM}	I_{FM} = 0.5 A	–	3.0	4.0	V
Reverse current	I_R	V_R = 3 V	–	–	10	µA
Radiant flux	ϕ_e	I_F = 20 mA	2.0	–	6.0	mW
Peak emission wavelength	λp	I_F = 5 mA	–	940	–	nm
Half intensity wavelength	Δλ	I_F = 5 mA	–	45	–	nm
Terminal capacitance	C_t	V_R = 0, f = 1 MHz	–	50	–	pF
Response frequency	f_C	–	–	300	–	kHz
Half intensity angle	Δθ	–	–	±10	–	degrees

Fig. 1 Forward Current vs. Ambient Temperature

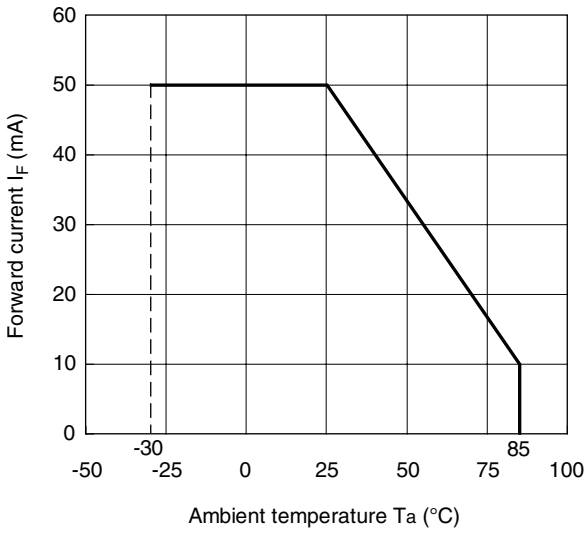


Fig. 2 Peak Forward Current vs. Duty Ratio

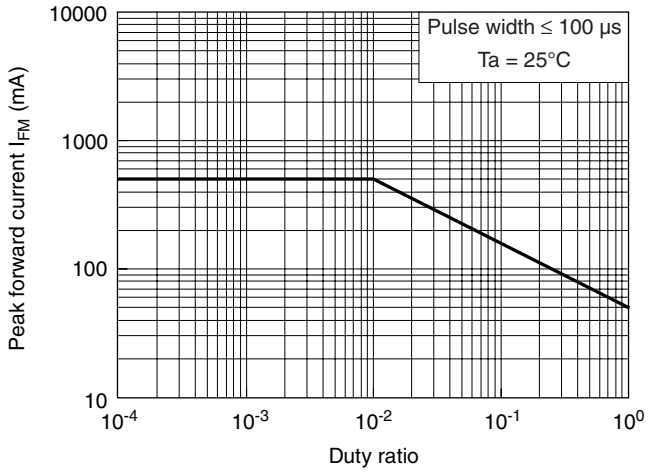


Fig. 3 Spectral Distribution

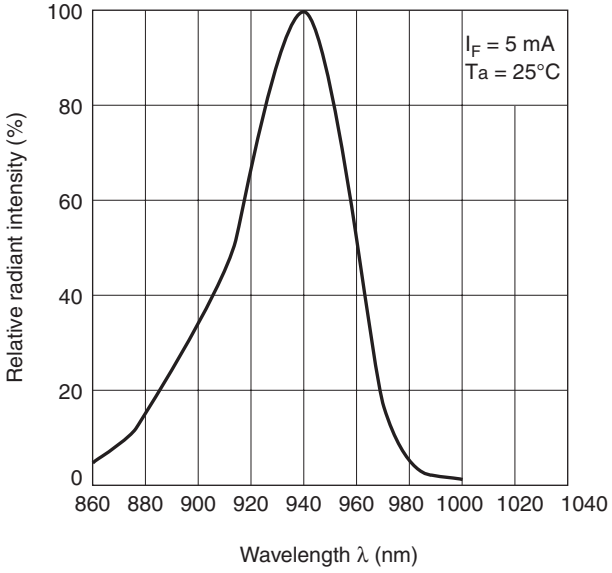


Fig. 4 Peak Emission Wavelength vs. Ambient Temperature

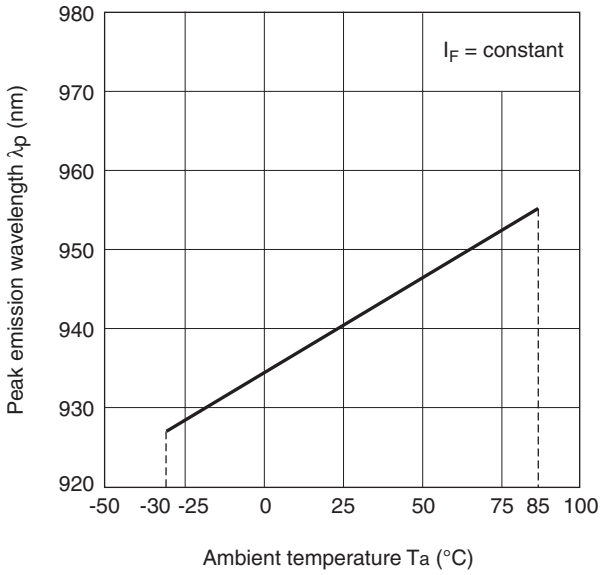


Fig. 5 Forward Current vs. Forward Voltage

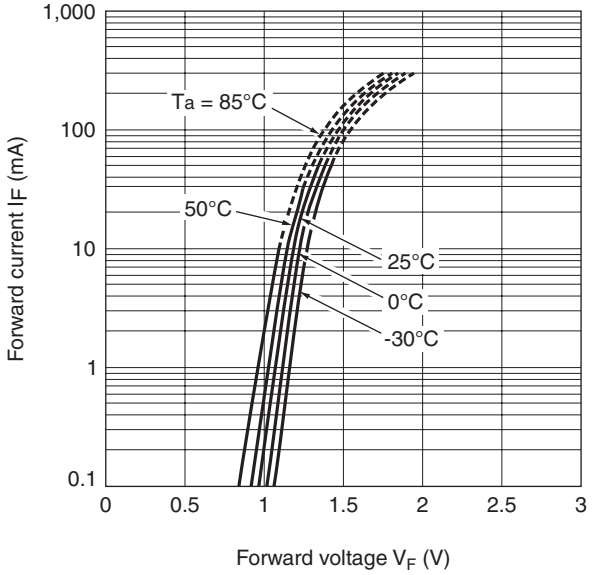


Fig. 6 Relative Radiant Flux vs. Ambient Temperature

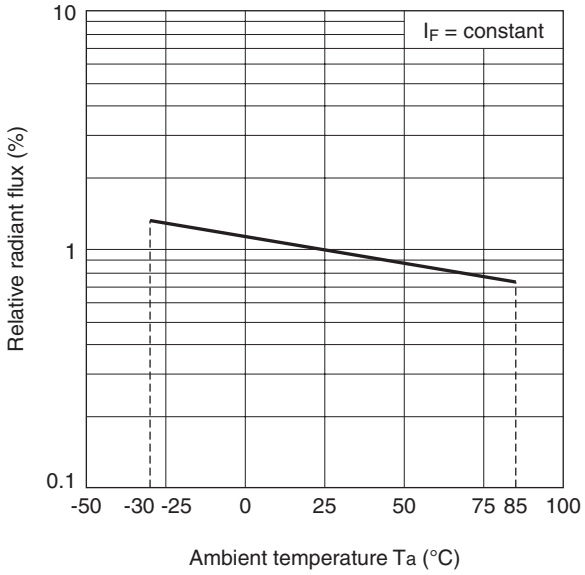


Fig. 7 Radiant Flux vs. Forward Current

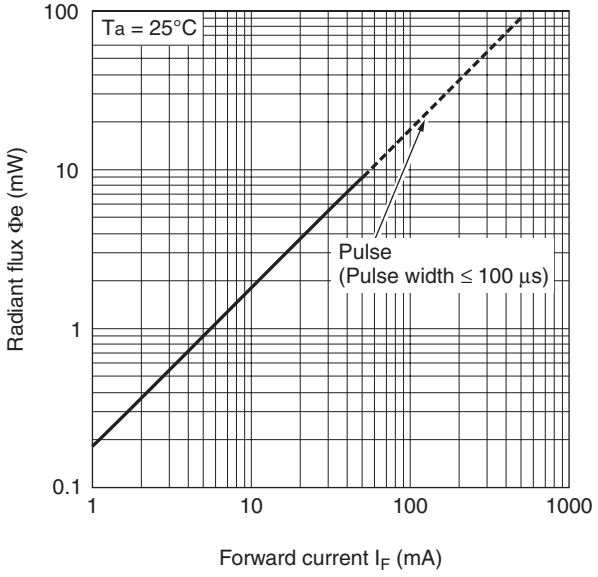


Fig. 9 Radiation Diagram (Typical Value)

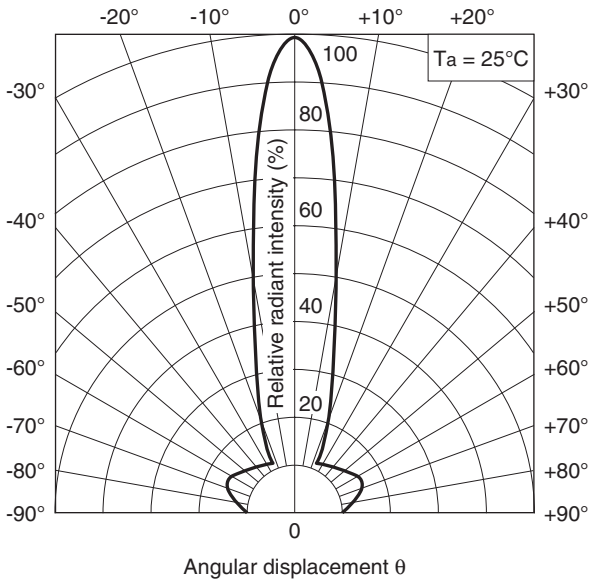
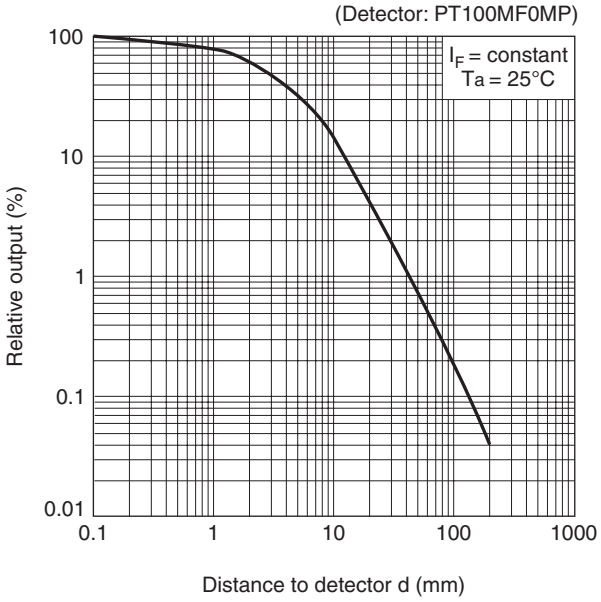


Fig. 8 Relative Output vs. Distance to Detector



■ Design Considerations

Design Guidelines

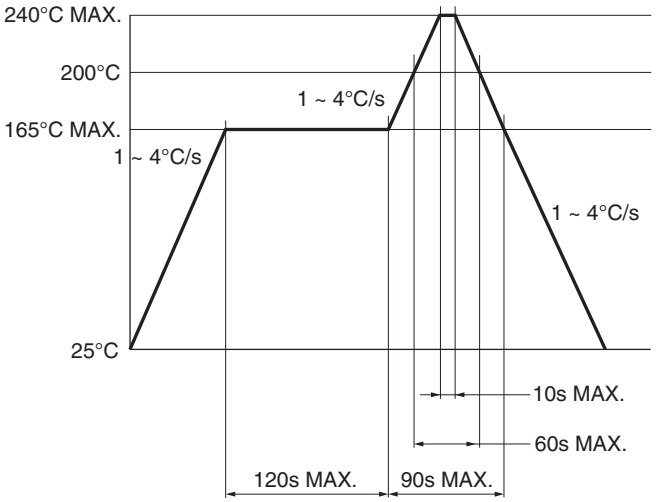
1. Allow for natural degradation of the LED as a result of long continuous operation. This part will have 50% degradation in output after 5 years of continuous use.
2. This product is not designed to be electromagnetic- and ionized-particle-radiation resistant.

■ Manufacturing Guidelines

Soldering Instructions

1. Sharp recommends soldering no more than once when using solder reflow methods.
2. When using solder reflow methods, follow the reflow soldering temperature profile shown in Fig. 10. Sharp recommends checking the process to make sure these parameters are not exceeded; exceeding these parameters can cause substrate bending or other mechanical stresses leading to debonding of the internal gold wires, or other similar failure modes.
3. If using an infrared lamp to preheat the parts, such heat sources may cause localized high temperatures in the part's resin. Be sure to keep the temperature profile within the guidelines shown in Fig. 10.
4. If hand soldering, use temperatures ≤260° for ≤3 seconds. Do not dip-solder or VPS-solder this part.
5. Do not subject the package to excessive mechanical force during soldering as it may cause deformation or defects in plated connections. Internal connections may be severed due to mechanical force placed on the package due to the PCB flexing during the soldering process.

Fig. 10 Reflow Soldering Temperature Profile



Cleaning Instructions

1. Confirm this device's resistance to process chemicals before use, as certain process chemicals may affect the optical characteristics.
2. Solvent cleaning: Solvent temperature should be 45°C or below. Immersion time should be 3 minutes or less.
3. Ultrasonic cleaning: The effect upon devices varies due to cleaning bath size, ultrasonic power output, cleaning time, PCB size and device mounting circumstances. Sharp recommends testing using actual production conditions to confirm the harmlessness of the ultrasonic cleaning methods.
4. Recommended solvent materials: Ethyl alcohol, Methyl alcohol, and Isopropyl alcohol.

Storage and Handling

1. Store these parts between 5°C and 30°C, at a relative humidity of less than 70%.
2. After breaking the package seal, maintain the environment within 5°C to 25°C, at a relative humidity of less than 60%, and mount the parts within two days. If unable to do so, bake before mounting.
3. When storing the parts after breaking the seal, Sharp recommends storage of no longer than two weeks in a dry box or by resealing the parts in a moisture-proof bag with a desiccant. If unable to do so, bake before mounting.
4. When baking the parts before mounting, Sharp recommends baking the parts only once and only if in a metal tray or mounted on a PCB. Recommended conditions are for 16 to 24 hours, at a temperature of 125°C.

■ Presence of ODCs (RoHS Compliance)

This product shall not contain the following materials, and they are not used in the production process for this product:

- Regulated substances: CFCs, Halon, Carbon tetrachloride, 1,1,1-Trichloroethane (Methylchloroform). Specific brominated flame retardants such as the PBBOs and PBBs are not used in this product at all.

This product shall not contain the following materials banned in the RoHS Directive (2002/95/EC).

- Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBB), Polybrominated diphenyl ethers (PBDE).
- Content information about the six substances specified in “Management Methods for Control of Pollution Caused by Electronic Information Products Regulation” (Chinese: 电子信息产品污染控制管理办法)

Category	Toxic and Hazdardous Substances					
	Lead (Pb)	mercury (Hg)	Cadmium (Cd)	Hexavalent chromiun (Cr^{6+})	Polybrominated biphenyls (PBB)	Polybrominated diphenyl ethers (PBDE)
Infrared Emitting Diode	✓	✓	✓	✓	✓	✓

NOTE: ✓ indicates that the content of the toxic and hazardous substance in all the homogeneous materials of the part is below the concentration limit requirement as described in SJ/T 11363-2006 standard.

■ Taping Specifications

1. Tape structure and dimensions conforms to those shown in Fig. 11 to Fig. 16.
2. Product insertion will have the cathode to the hole side of the tape.
3. Cover tape peel-separation force: F = 0.2 to 1.0 N (where θ 160° to 180°)
4. Quantity per reel = 2000 pcs. (GL100MN1MP) or 1500 pcs. (GL100MN1MP1)
5. Product mass: 0.01 g (approx.)
6. Packaging:
   a. Reels are sealed inside an aluminum bag, along with a humidity indicator card.
   b. Bags are labeled and securely packed.

■ Packing Specifications

● GL100MN1MP (Side view mount, 2000 pcs/reel)

Fig. 11 Tape Shape and Dimension

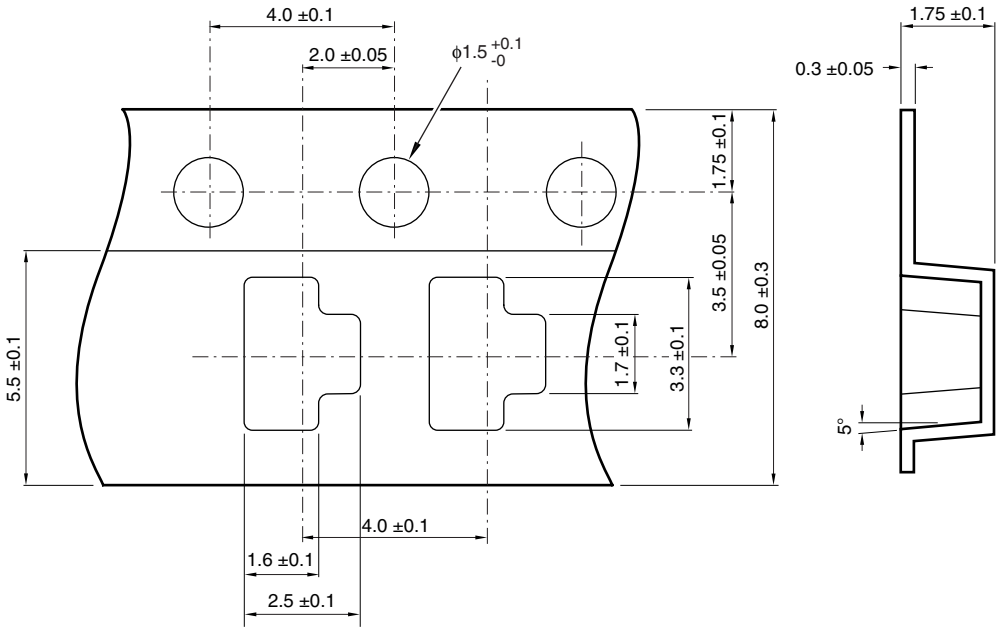
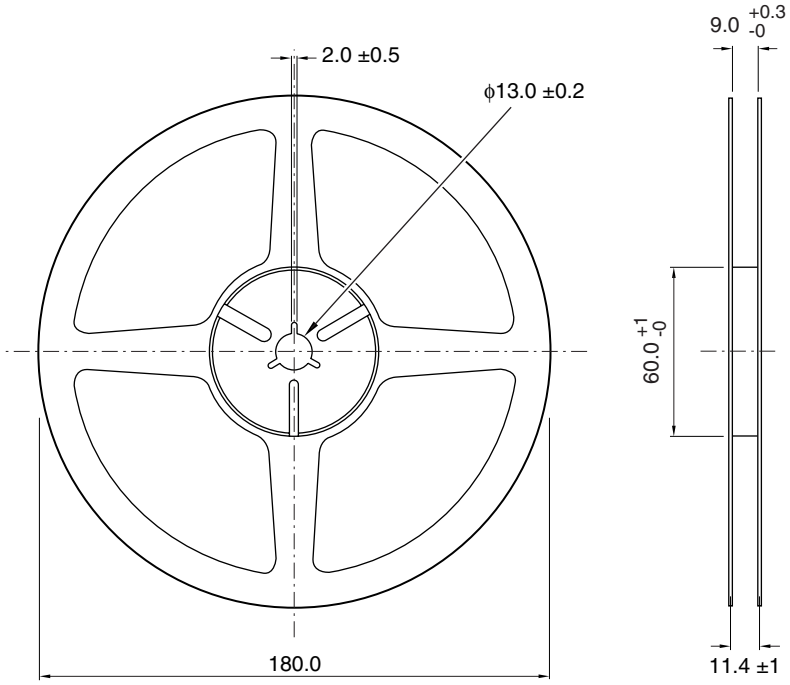
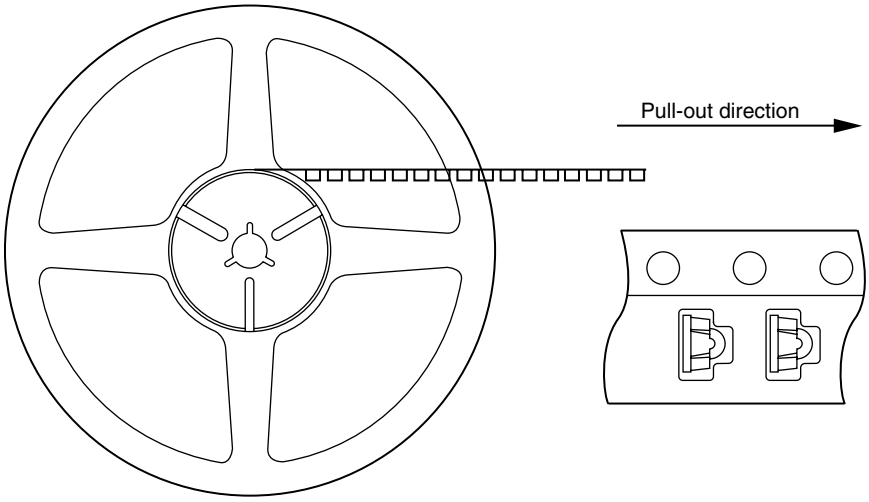


Fig. 12 Reel Shape and Dimension



NOTE: Unit: mm

Fig. 13 Product Insertion Direction



● GL100MN1MP1 (Top view mount, 1500 pcs/reel)

Fig. 14 Tape Shape and Dimension

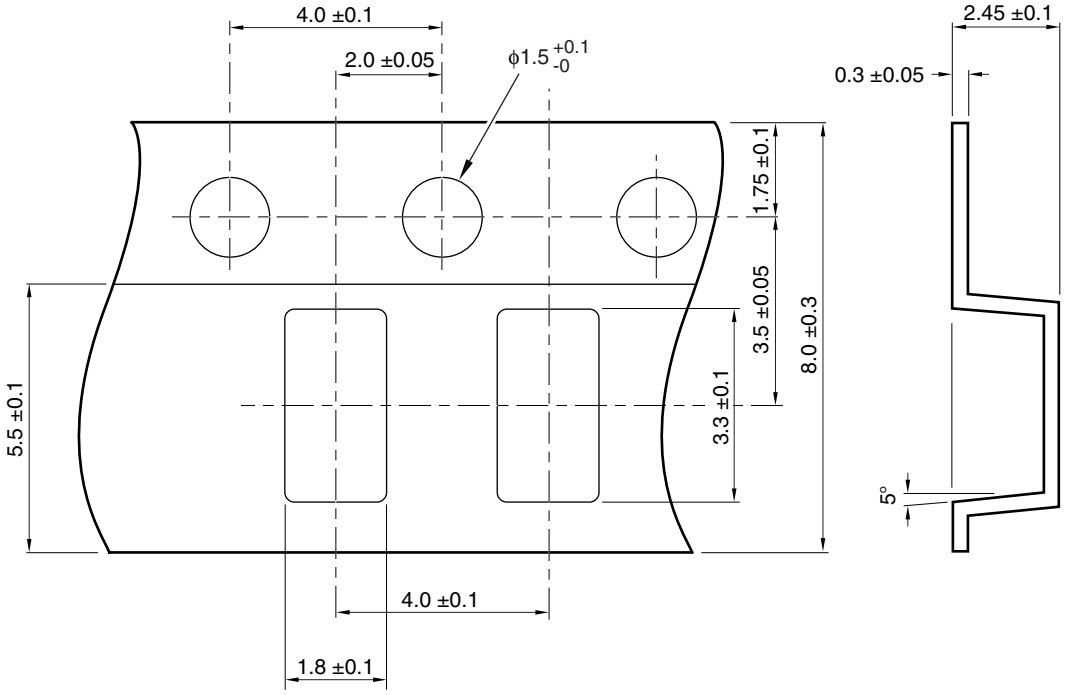
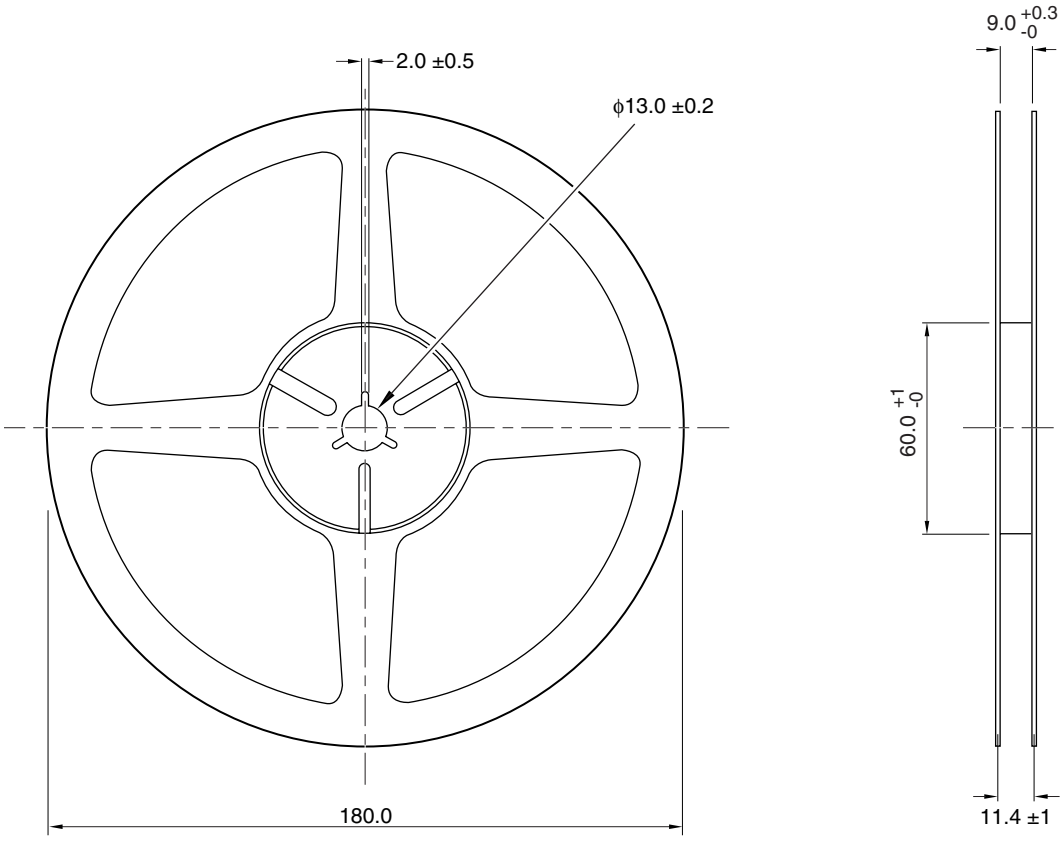
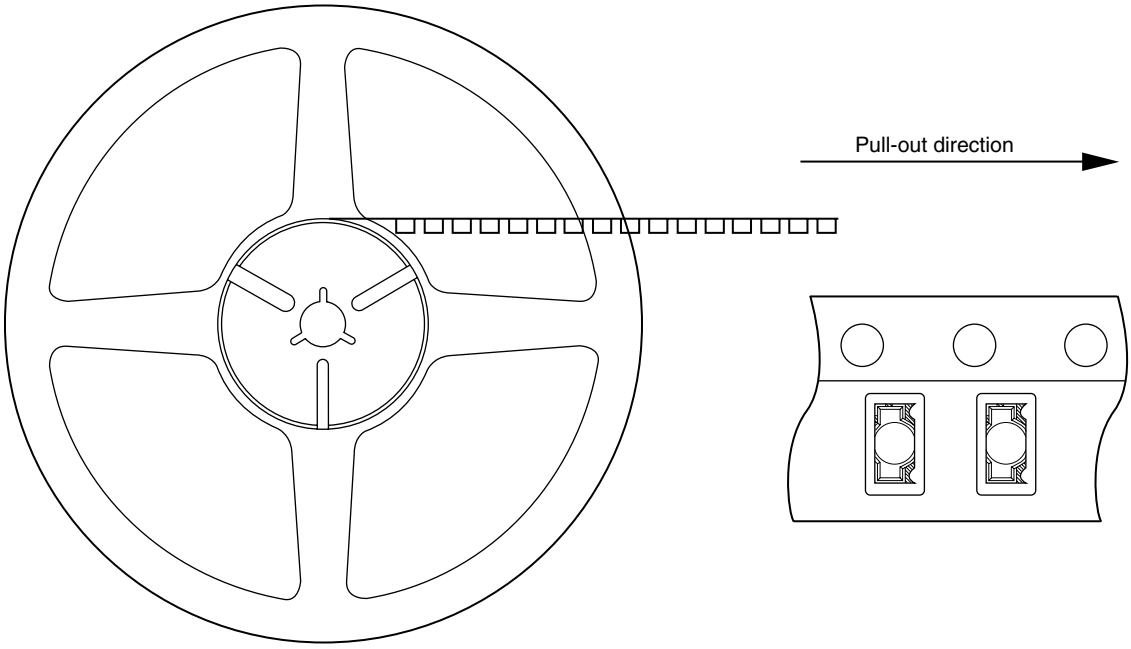


Fig. 15 Reel Shape and Dimension



NOTE: Unit: mm

Fig. 16 Product Insertion Direction



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--- Industrial control
--- Audio visual equipment
--- Consumer electronics

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--- Gas leakage sensor breakers
--- Alarm equipment
--- Various safety devices, etc.

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